



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 53686  
Application ID: 10667227  
Title of Invention: SEMICONDUCTOR PACKAGE AND  
METHOD OF MAKING USING  
LEADFRAME HAVING LEAD  
LOCKS TO SECURE LEADS TO  
ENCAPSULANT  
First Named Inventor: Jae Yee  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-09-18  
Effective Receipt Date: 2004-01-14  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 7012  
Attorney Docket Number: AMKOR012G1



Total Fees Authorized:


Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 305399c5c7ac9ae1914dbdfef3de5511a6e77f60



## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING USING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids1-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING USING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT
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Application Number: 10/667227



Confirmation Number: 7012

First Named Applicant: Jae Yee

Attorney Docket Number: AMKOR012G1

Art Unit: 2812

Search string: ( 2596993 or 3435815 or 3734660 or 3838984  
or 4054238 or 4189342 or 4258381 or 4289922  
or 4301464 or 4332537 or 4417266 or 4451224  
or 4530152 or 4541003 or 4646710 or 4707724  
or 4727633 or 4737839 or 4756080 or 4812896  
or 4862245 or 4862246 or 4907067 or 4920074  
or 4935803 or 4942454 or 4987475 or 5018003  
or 5029386 or 5041902 or 5057900 or 5059379  
or 5065223 or 5070039 or 5087961 or 5091341  
or 5096852 or 5118298 or 5151039 or 5157475  
or 5157480 or 5168368 or 5172213 or 5172214  
or 5175060 or 5200362 or 5200809 or 5214845  
or 5216278 or 5218231 or 20010008305 or  
20010014538 or 20010011654 or 20020024122  
or 20020027297 or 20020140061 or  
20020140068 or 20020163015 or 20030030131  
or 20030073265 ).pn.

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	3435815	1969-04-01	FORCIER			
	3	3734660	1973-05-22	DAVIES ET AL.			
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	9	4301464	1981-11-17	OTSUKI ET AL.
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	12	4451224	1984-05-29	HARDING
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	50	5218231	1993-06-08	KUDO

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010008305	2001-07-19	MCLELLAN ET AL.			
	2	20010014538	2001-08-16	KWAN ET AL.			
	3	20010011654	2002-01-31	KIMURA			
	4	20020024122	2002-02-28	JUNG ET AL.			
	5	20020027297	2002-03-07	IKENAGA ET AL.			
	6	20020140061	2002-10-03	LEE			
	7	20020140068	2002-10-03	LEE ET AL.			
	8	20020163015	2002-11-07	LEE ET AL.			
	9	20030030131	2003-02-13	LEE ET AL.			
	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date